

ELECTRONIC COMPONENTS, PACKAGING AND PRODUCTION

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The book is primarily meant for university education in introductory electronic packaging technology. An overview is given, that encompasses aspects of material technology, metallurgy, chemistry, physical properties, and mechanical properties. An understanding of the interplay of all these basic fields is necessary for choosing and using the available packaging technologies optimally, making a good design that can result in a product with the right quality. Component technologies are described, basic processing methods, printed wiring boards, design guidelines, the production of printed circuit boards and the common hybrid technologies, including multichip modules.

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The first edition was published in 1993. The most important change in this revised edition from 1995 is an additional chapter on micromachined devices. (Chapter 9) The other chapters have only minor changes.

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